

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph beginning at page 3, line 10, as indicated below:

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An aspect of the present invention involves a method of transferring wafers between a thermal treatment chamber and a thermal treatment installation. The treatment chamber has a top section and a bottom section between which the wafer is accommodated during treatment. The thermal treatment installation has a loading chamber in which one wafer of a set of wafers is combined with a ring in a wafer/ring combination. The loading chamber ~~has~~having loading means for placing a wafer on a wafer support and transport means for moving the wafer/ring combination. The wafer is placed on ~~[[a]]~~the wafer support with the loading means while in the loading chamber, wherein the wafer support is configured as a ring having support elements to support the wafer. The wafer support loaded with the wafer is inserted into the thermal treatment chamber using the transport means so that the wafer and the wafer support are positioned between the top section and the bottom section. The wafer is individually processed in the thermal treatment chamber. After processing the wafer, the wafer support is removed from the thermal treatment chamber.